

# XC822/824

8-Bit Single-Chip Microcontroller

Data Sheet

V0.1 2010-02

Microcontrollers

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Microcontrollers

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Preliminary

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**XC822/824 Data Sheet**

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**Revision History: V0.1 2010-02**

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Previous Versions:

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Page	Subjects (major changes since last revision)
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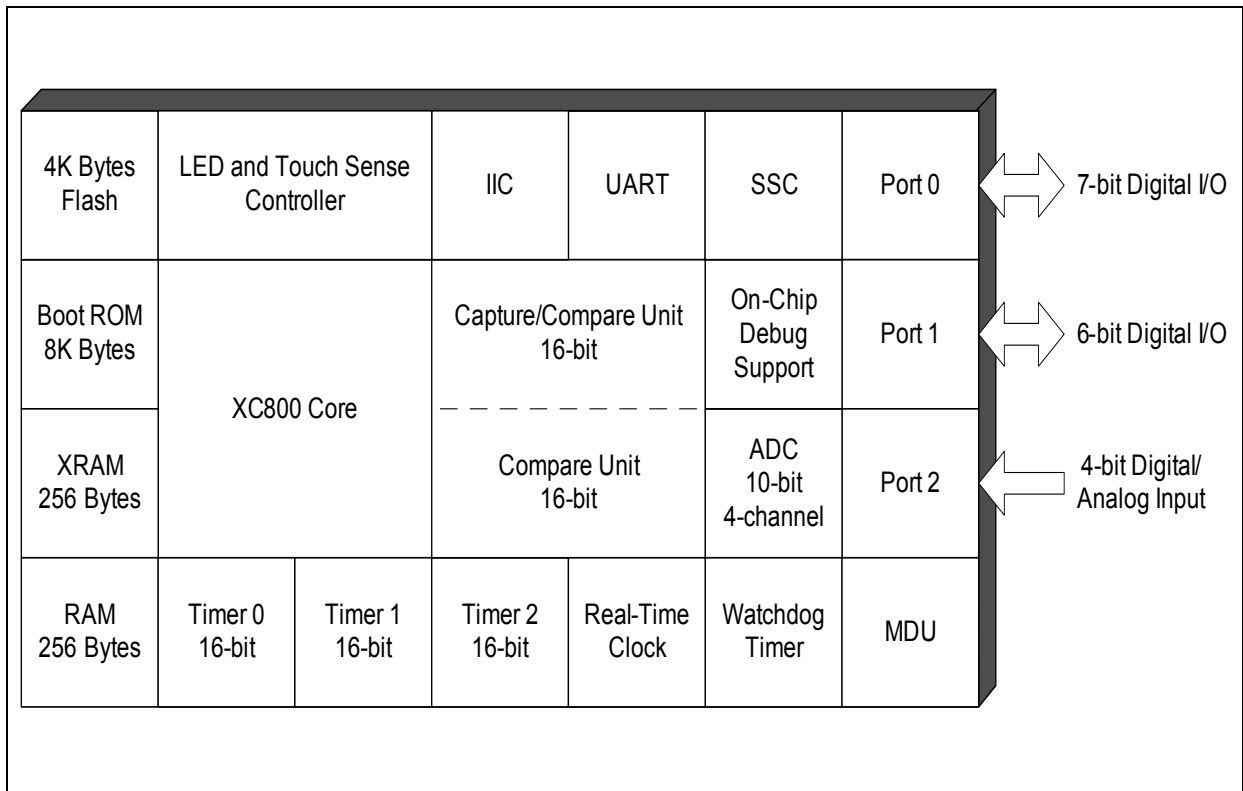
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# 1 Summary of Features

The XC822/824 has the following features:

- High-performance XC800 Core
  - compatible with standard 8051 processor
  - two clocks per machine cycle architecture (for memory access without wait state)
  - two data pointers
- On-chip memory
  - 8 Kbytes of Boot ROM, Library ROM and User routines
  - 256 bytes of RAM
  - 256 bytes of XRAM
  - 4 Kbytes of Flash (includes memory protection strategy)
- I/O port supply at 2.5 V - 5.5 V and core logic supply at 2.5 V (generated by embedded voltage regulator)



**Figure 1 XC878 Functional Units**

- Power-on reset generation
- Brownout detection for IO supply and core logic supply
- 48 MHz on-chip OSC for clock generation
  - Loss-of-Clock detection

(more features on next page)

Features: (continued)

- Power saving modes
  - idle mode
  - power-down mode with wake-up capability via real-time clock interrupt
  - clock gating control to each peripheral
- Programmable 16-bit Watchdog Timer (WDT) running on independent oscillator with programmable window feature for refresh operation and warning prior to overflow
- Three ports
  - Up to 17 pins as digital I/O
  - 4 pin as digital/analog input
- 4-channel, 10-bit ADC
  - support up to 3 differential input channel
  - results filtering by data reduction or digital low-pass filter, for up to 13-bit results
- Up to 4 channels, Out of range comparator
- Three 16-bit timers
  - Timer 0 and Timer 1 (T0 and T1)
  - Timer 2 (T2)
- Periodic wake-up timer
- Multiplication/Division Unit for arithmetic operations (MDU)
- Capture and Compare unit for PWM signal generation (CCU6)
- A full-duplex or half-duplex serial interface (UART)
- Synchronous serial channel (SSC)
- Inter-IC (IIC) serial interface
- LED and Touch-sense Controller (LEDTSCU)
- On-chip debug support via single pin DAP interface (SPD)
- Packages:
  - PG-DSO-20
  - PG-TSSOP-16
- Temperature range  $T_A$ :
  - SAF (-40 to 85 °C)
  - SAK (-40 to 125 °C)

**XC822/824 Variant Devices**

The XC822/824 product family features devices with different configurations, program memory sizes, packages options and temperature profiles, to offer cost-effective solutions for different application requirements.

The list of XC822/824 device configurations are summarized in **Table 1**. The type of packages available are TSSOP-16 for XC822 and DSO-20 for XC824.

**Table 1 Device Configuration**

Device Name	MDU Module	LEDTSCU Module
XC822/824	No	No
XC822/824M	Yes	No
XC822/824T	No	Yes
XC822/824MT	Yes	Yes

**Table 2** shows the device sales type available, based on above device.

**Table 2 Device Profile**

Sales Type	Device Type	Program Memory (Kbytes)	Temperature Profile (°C)	Package Type	Quality Profile
SAF-XC822T-0FRI	Flash	2	-40 to 85	PG-TSSOP-16	Industrial
SAF-XC822-1FRI	Flash	4	-40 to 85	PG-TSSOP-16	Industrial
SAF-XC822T-1FRI	Flash	4	-40 to 85	PG-TSSOP-16	Industrial
SAF-XC822M-1FRI	Flash	4	-40 to 85	PG-TSSOP-16	Industrial
SAF-XC822MT-1FRI	Flash	4	-40 to 85	PG-TSSOP-16	Industrial
SAF-XC824M-1FGI	Flash	4	-40 to 85	PG-DSO-20	Industrial
SAF-XC824MT-1FGI	Flash	4	-40 to 85	PG-DSO-20	Industrial
SAK-XC824M-1FGI	Flash	4	-40 to 125	PG-DSO-20	Industrial

As this document refers to all the derivatives, some description may not apply to a specific product. For simplicity, all versions are referred to by the term XC822/824 throughout this document.

**Ordering Information**

The ordering code for Infineon Technologies microcontrollers provides an exact reference to the required product. This ordering code identifies:



**Preliminary****Summary of Features**

- The derivative itself, i.e. its function set, the temperature range, and the supply voltage
- The package and the type of delivery

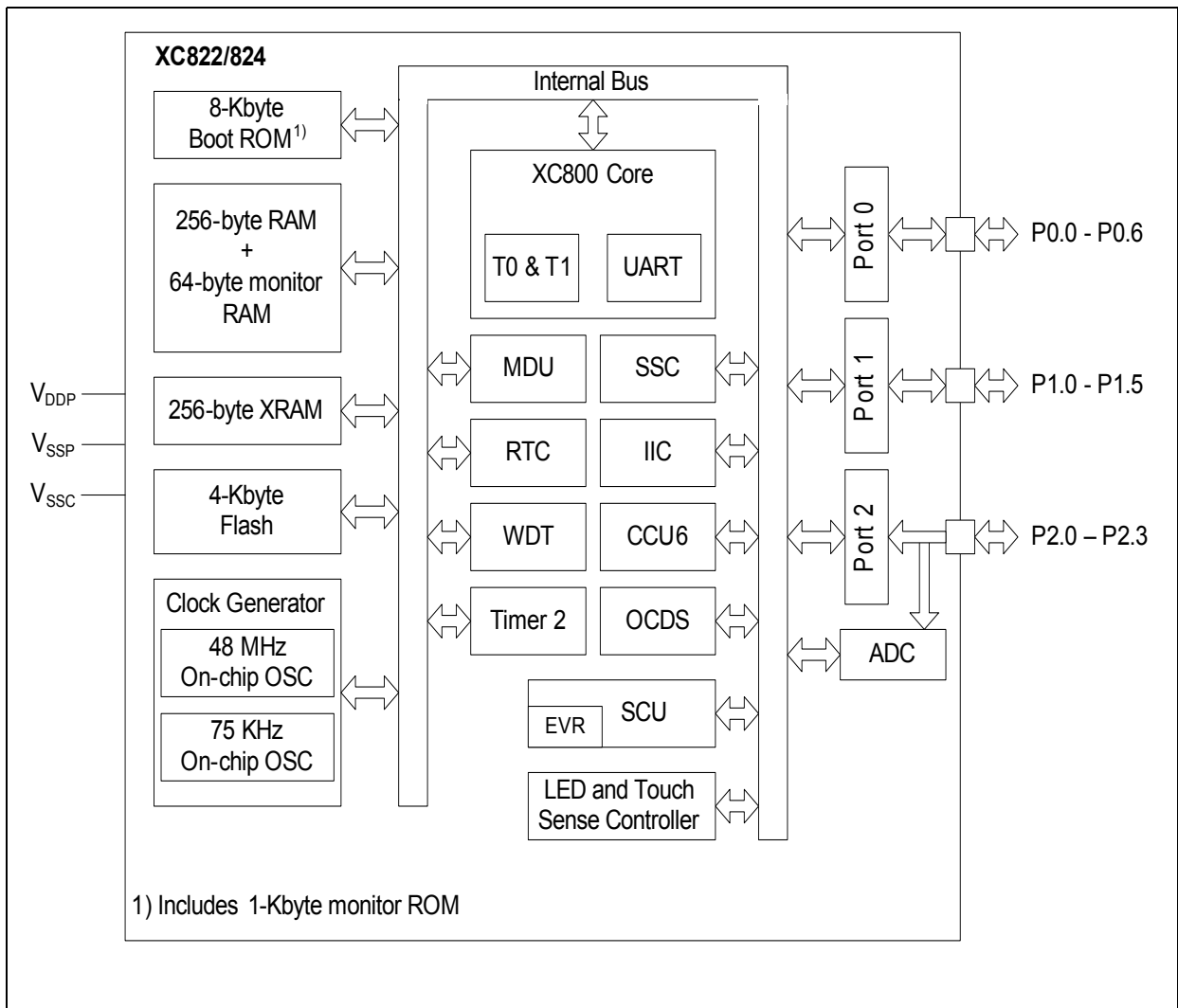
For the available ordering codes for the XC822/824, please refer to your responsible sales representative or your local distributor.

## 2 General Device Information

**Chapter 2** contains the block diagram, pin configurations, definitions and functions of the XC822/824.

### 2.1 Block Diagram

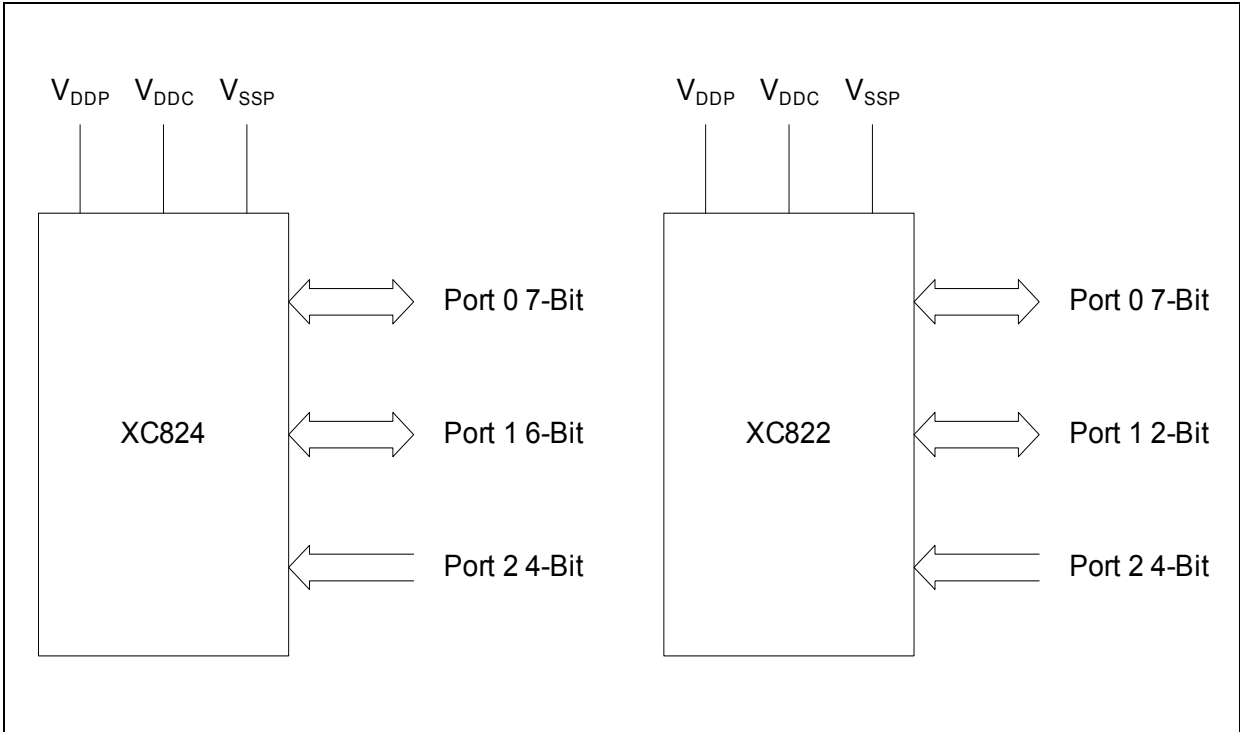
The block diagram of the XC822/824 is shown in **Figure 2**.



**Figure 2 XC822/824 Block Diagram**

## 2.2 Logic Symbol

The logic symbol of the XC822/824 is shown in [Figure 3](#).



**Figure 3** XC822/824 Logic Symbol

### 2.3 Pin Configuration

The pin configuration of the XC822 in [Figure 4](#).

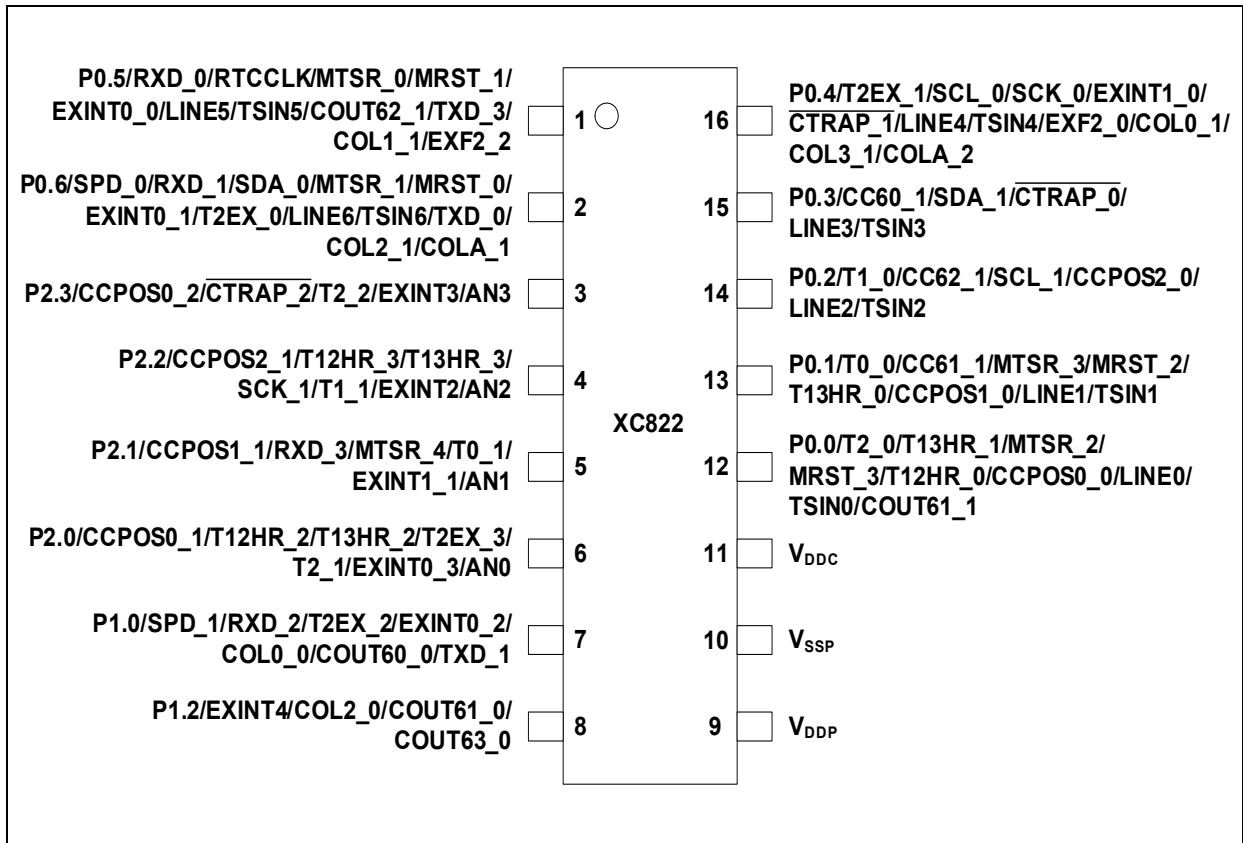


Figure 4 XC822 Pin Configuration, PG-TSSOP-16 Package (top view)

The pin configuration of the XC824 in [Figure 5](#).

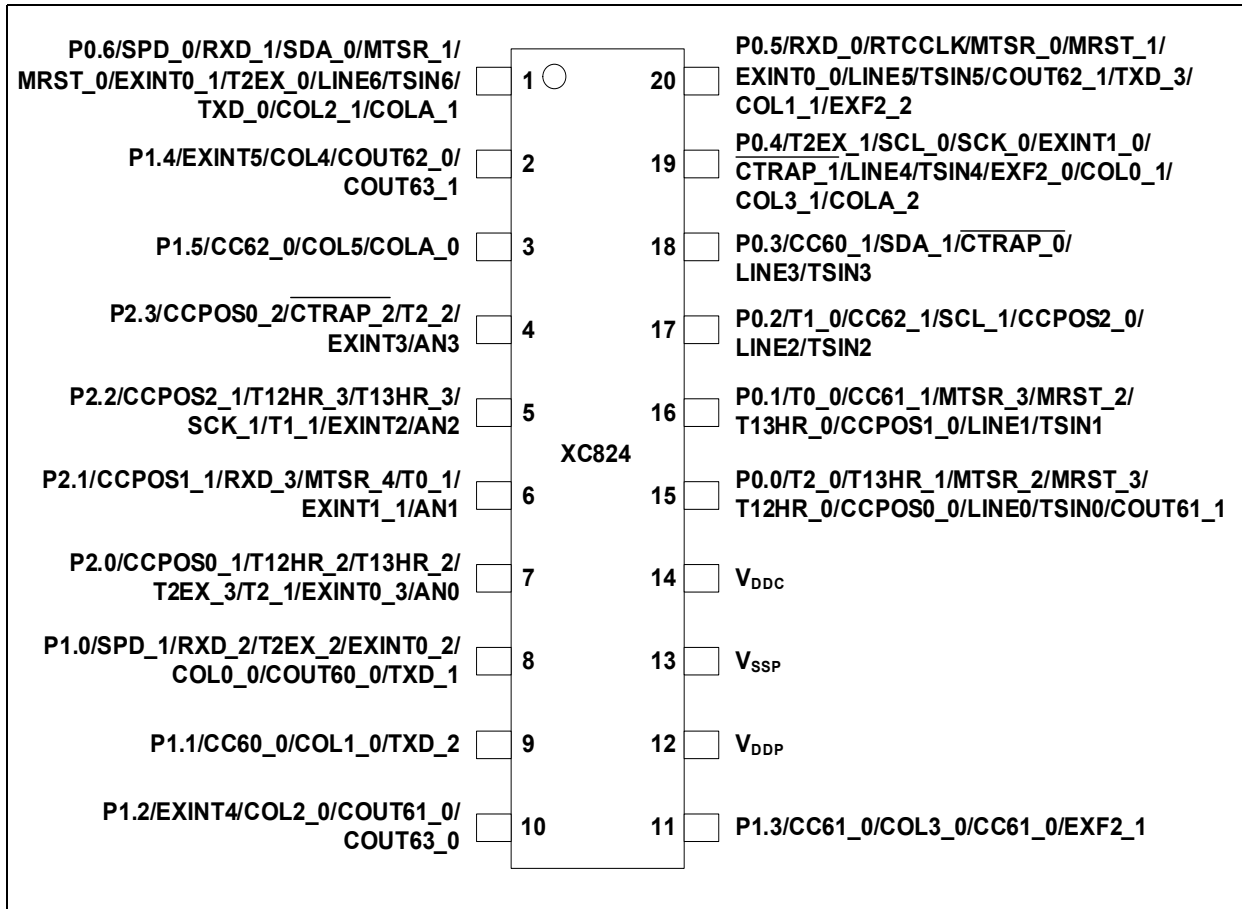


Figure 5 XC824 Pin Configuration, PG-DSO-20 Package (top view)

## 2.4 Pin Definitions and Functions

The functions and default states of the XC822/824 external pins are provided in [Table 3](#).

**Table 3 Pin Definitions and Functions for XC822/824**

Symbol	Pin Number DSO20/ TSSOP16	Type	Reset State	Function
<b>P0</b>		I/O		<b>Port 0</b> Port 0 is a bidirectional general purpose I/O port. It can be used as alternate functions for LEDTSCU, Timer 0, 1 and 2, SSC, CCU6, IIC, SPD and UART.
P0.0	15/12		Hi-Z	T2_0            Timer 2 Input T13HR_1        CCU6 Timer 13 Hardware Run Input MTSR_2         SSC Master Transmit Output/ Slave Receive Input MRST_3        SSC Master Receive Input T12HR_0        CCU6 Timer 12 Hardware Run Input CCPOS0_0      CCU6 Hall Input 0 TSIN0           Touch-sense Input 0 LINE0           LED Line 0 COUT61_1      Output of Capture/Compare Channel 1

**Table 3 Pin Definitions and Functions for XC822/824**

Symbol	Pin Number DSO20/ TSSOP16	Type	Reset State	Function
P0.1	16/13		Hi-Z	T0_0      Timer 0 Input CC61_1    Input/Output of Capture/Compare channel 1 MTSR_3    SSC Slave Receive Input MRST_2    SSC Master Receive Input/ Slave Transmit Output T13HR_0    CCU6 Timer 13 Hardware Run Input CCPOS1_0   CCU6 Hall Input 1 TSIN1      Touch-sense Input 1 LINE1      LED Line 1
P0.2	17/14		Hi-Z	T1_0      Timer 1 Input CC62_1    Input/Output of Capture/Compare channel 1 SCL_1      IIC Clock Line CCPOS2_0   CCU6 Hall Input 2 TSIN2      Touch-sense Input 2 LINE2      LED Line 2
P0.3	18/15		Hi-Z	CC60_1    Input/Output of Capture/Compare channel 1 SDA_1      IIC Data Line CTRAP_0    CCU6 Trap Input TSIN3      Touch-sense Input 3 LINE3      LED Line 3

**Table 3 Pin Definitions and Functions for XC822/824**

Symbol	Pin Number DSO20/ TSSOP16	Type	Reset State	Function	
P0.4	19/16		PD	T2EX_1	Timer 2 External Trigger Input
				SCK_0	SSC Clock Input/Output
				SCL_0	IIC Clock Line
				CTRAP_1	CCU6 Trap Input
				EXINT1_0	External Interrupt Input 1
				TSIN4	Touch-sense Input 4
				LINE4	LED Line 4
				EXF2_0	Timer 2 Overflow Flag
				COL0_1	LED Column 0
				COL3_1	LED Column 3
COLA_2	LED Column A				
P0.5	20/1		Hi-Z	RXD_0	UART Receive Input
				RTCCLK	RTC External Clock Input
				MTSR_0	SSC Master Transmit Output/ Slave Receive Input
				MRST_1	SSC Master Receive Input
				EXINT0_0	External Interrupt Input 0
				TSIN5	Touch-sense Input 5
				LINE5	LED Line 5
				COU62_1	Output of Capture/Compare Channel 2
				TXD_3	UART Transmit Output/ 2-wire UART BSL Transmit Output
				COL1_1	LED Column 1
EXF2_2	Timer 2 Overflow Flag				



**Table 3 Pin Definitions and Functions for XC822/824**

Symbol	Pin Number DSO20/ TSSOP16	Type	Reset State	Function
P0.6	1/2		PU	SPD_0      SPD Input/Output RXD_1      UART Receive Input/ UART BSL Receive Input SDA_0      IIC Data Line MTSR_1     SSC Slave Receive Input MRST_0     SSC Master Receive Input/ Slave Transmit Output EXINT0_1   External Interrupt Input 0 T2EX_0     Timer 2 External Trigger Input TSIN6      Touch-sense Input 6 LINE6      LED Line 6 TXD_0      UART Transmit Output/ 1-wire UART BSL Transmit Output COL2_1     LED Column 2 COLA_1     LED Column A
<b>P1</b>		I/O		<b>Port 1</b> Port 1 is a bidirectional general purpose I/O port. It can be used as alternate functions for CCU6, LEDTSCU, SPD, UART and Timer 2.
P1.0	8/7		Hi-Z	SPD_1      SPD Input/Output RXD_2      UART Receive Input T2EX_2     Timer 2 External Trigger Input EXINT0_2   External Interrupt Input 0 COL0_0     LED Column 0 COUT60_0   Output of Capture/Compare Channel 0 TXD_1      UART Transmit Output

**Table 3 Pin Definitions and Functions for XC822/824**

Symbol	Pin Number DSO20/ TSSOP16	Type	Reset State	Function
P1.1	9/-		Hi-Z	CC60_0    Input/Output of Capture/Compare channel 0 COL1_0    LED Column 1 TXD_2    UART Transmit Output
P1.2	10/8		Hi-Z	EXINT4    External Interrupt Input 4 COL2_0    LED Column 2 COUT61_0    Output of Capture/Compare channel 1 COUT63_0    Output of Capture/Compare channel 3
P1.3	11/-		Hi-Z	CC61_0    Input/Output of Capture/Compare channel 1 COL3_0    LED Column 3 EXF2_1    Timer 2 Overflow Flag
P1.4	2/-		Hi-Z	EXINT5    External Interrupt Input 5 COL4    LED Column 4 COUT62_0    Output of Capture/Compare channel 2 COUT63_1    Output of Capture/Compare channel 3
P1.5	3/-		Hi-Z	CC62_0    Input/Output of Capture/Compare channel 2 COL5    LED Column 5 COLA_0    LED Column A
<b>P2</b>		I		<b>Port 2</b> Port 2 is a general purpose input-only port. It can be used as inputs for A/D Converter and out of range comparator, CCU6, Timer 2, SSC and UART.

**Table 3 Pin Definitions and Functions for XC822/824**

Symbol	Pin Number DSO20/ TSSOP16	Type	Reset State	Function
P2.0	7/6		Hi-Z	CCPOS0_1    CCU6 Hall Input 0 T12HR_2    CCU6 Timer 12 Hardware Run Input T13HR_2    CCU6 Timer 13 Hardware Run Input T2EX_3    Timer 2 External Trigger Input T2_1    Timer 2 Input EXINT0_3    External Interrupt Input 0 AN0    Analog Input 0 / Out of range comparator channel 0
P2.1	6/5		Hi-Z	CCPOS1_1    CCU6 Hall Input 1 RXD_3    UART Receive Input MTSR_4    Slave Receive Input T0_1    Timer 0 Input EXINT1_1    External Interrupt Input 1 AN1    Analog Input 1 / Out of range comparator channel 1
P2.2	5/4		Hi-Z	CCPOS2_1    CCU6 Hall Input 2 T12HR_3    CCU6 Timer 12 Hardware Run Input T13HR_3    CCU6 Timer 13 Hardware Run Input SCK_1    SSC Clock Input/Output T1_1    Timer 1 Input EXINT2    External Interrupt Input 2 AN2    Analog Input 2 / Out of range comparator channel 2

**Table 3 Pin Definitions and Functions for XC822/824**

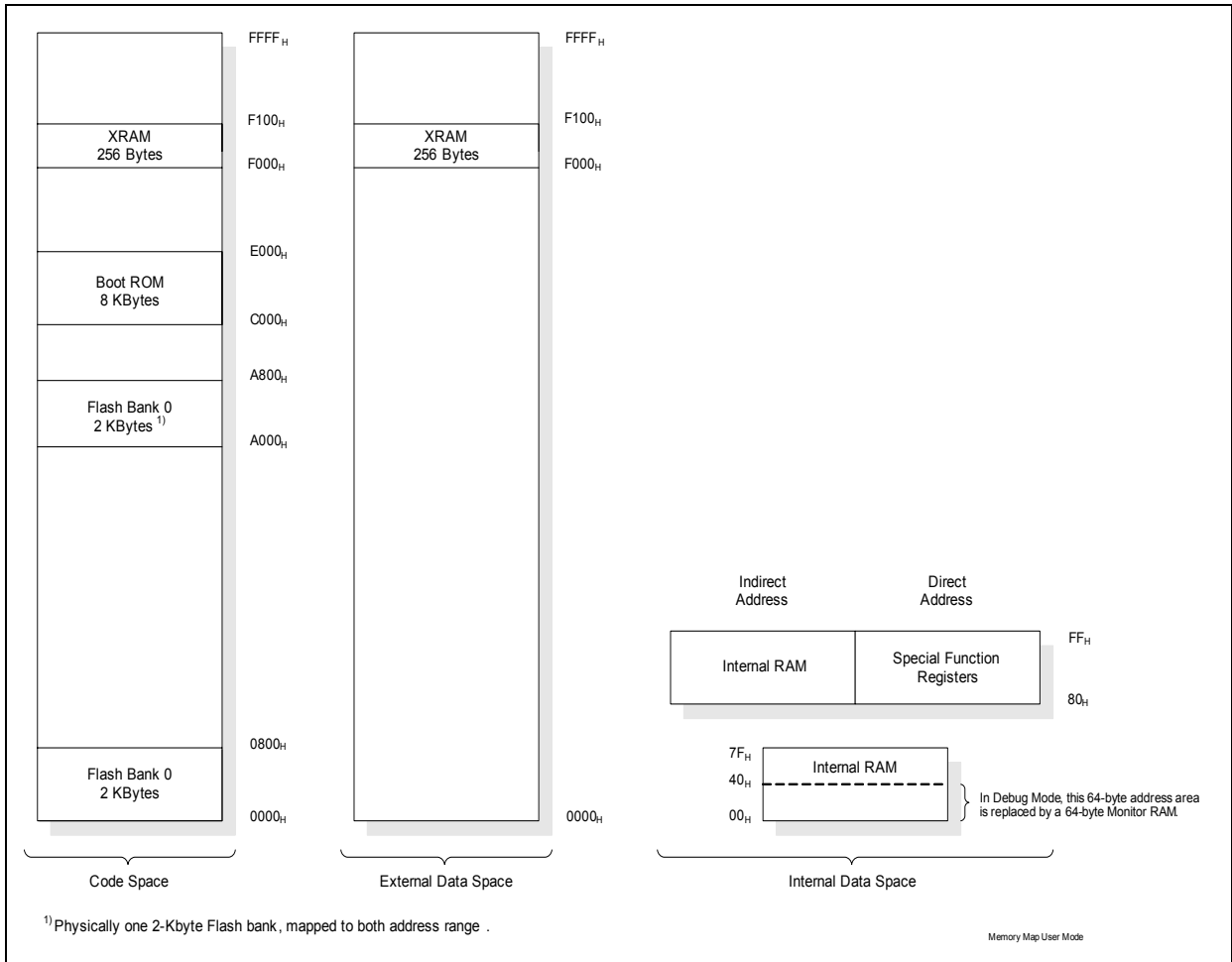
Symbol	Pin Number DSO20/ TSSOP16	Type	Reset State	Function
P2.3	4/3		Hi-Z	CCPOS0_2    CCU6 Hall Input 0 CTRAP_2    CCU6 Trap Input T2_2        Timer 2 Input EXINT3      External Interrupt Input 3 AN3         Analog Input 3 / Out of range comparator channel 3
V <sub>DDP</sub>	12/9	–		I/O Port Supply (2.5 V - 5.5 V)
V <sub>DDC</sub>	14/11	–		Core Supply Output (2.5 V)
V <sub>SSP</sub> / V <sub>SSC</sub>	13/10	–		I/O Port Ground/ Core Supply Ground

## 2.5 Memory Organization

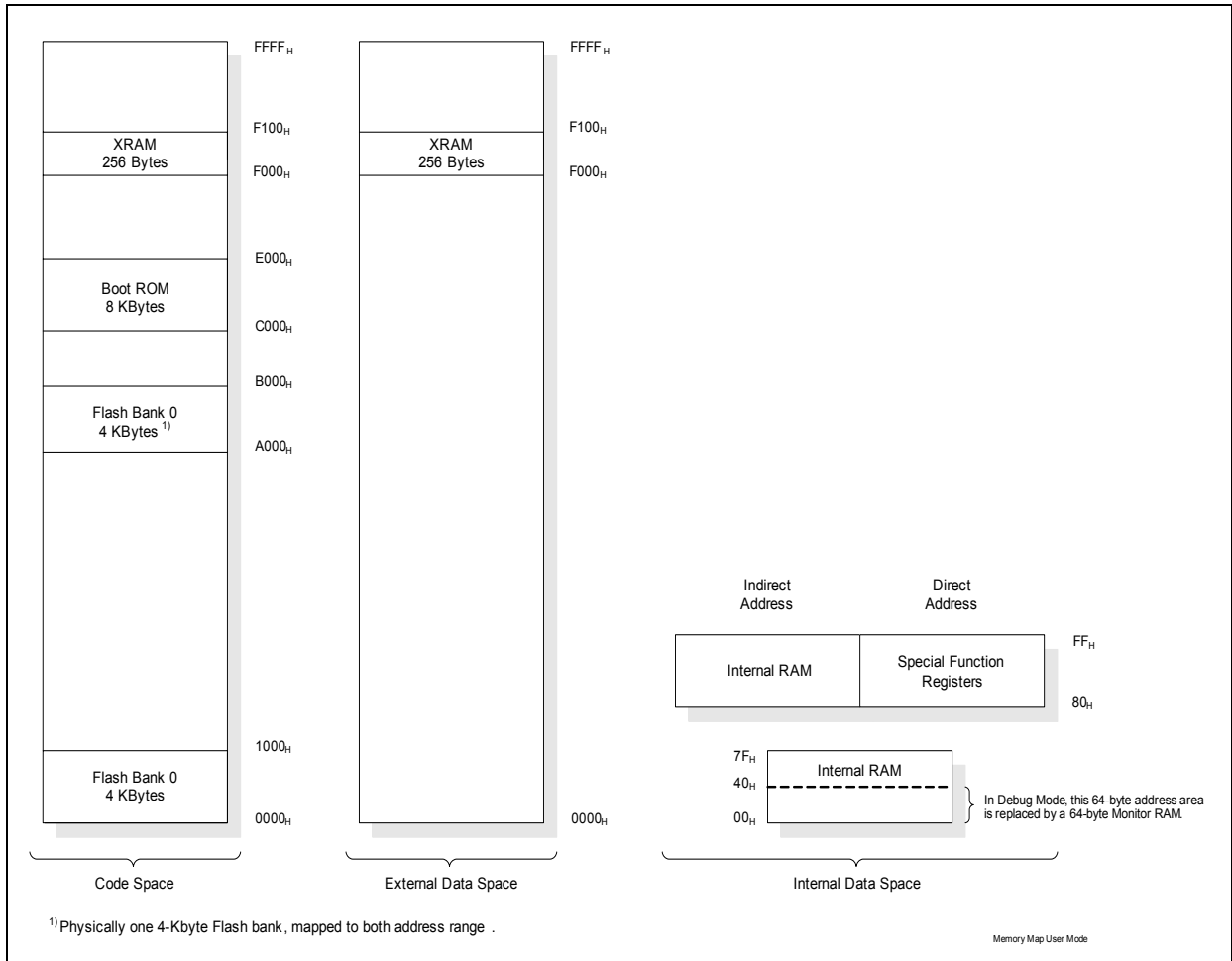
The XC822/824 CPU operates in the following five address spaces:

- 8 Kbytes of Boot ROM, Library ROM and User routines
- 256 bytes of internal RAM
- 256 bytes of XRAM  
(XRAM can be read/written as program memory or external data memory)
- A 128-byte Special Function Register area
- 2/4 Kbytes of Flash

**Figure 6** illustrates the memory address spaces of the 2 Kbyte Flash devices. **Figure 7** illustrates the memory address spaces of the 4 Kbyte Flash devices.



**Figure 6** Memory Map of XC822/824 with 2 Kbytes of Flash memory



**Figure 7 Memory Map of XC822/824 with 4 Kbytes of Flash memory**

## 2.6 JTAG ID

JTAG ID register is a read-only register located inside the JTAG module, and is used to recognize the device(s) connected to the JTAG interface. Its content is shifted out when INSTRUCTION register contains the IDCODE command (opcode 04<sub>H</sub>), and the same is also true immediately after reset.

The JTAG ID register contents for the XC822/824 Flash devices are given in [Table 4](#).

**Table 4 JTAG ID Summary**

Device Type	Device Name	JTAG ID
Flash	XC822/824*	101B C083 <sub>H</sub>

*Note: The asterisk (\*) above denotes all possible device configurations.*

## 2.7 Chip Identification Number

The XC822/824 identity (ID) register is located at Page 1 of address B3<sub>H</sub>. The value of ID register is 51<sub>H</sub>. However, for easy identification of product variants, the Chip Identification Number, which is a unique number assigned to each product variant, is available. The differentiation is based on the product and variant type information.

Two methods are provided to read a device's Chip Identification number:

- In-application subroutine, GET\_CHIP\_INFO
- Boot-loader (BSL) mode A

**Table 5** lists the Chip Identification numbers of XC822/824 device variants.

**Table 5 Chip Identification Number**

Product Variant	Chip Identification Number
XC822T-0FRI	51080243 <sub>H</sub>
XC822-1FRI	51080163 <sub>H</sub>
XC822T-1FRI	51080143 <sub>H</sub>
XC822M-1FRI	51080123 <sub>H</sub>
XC822MT-1FRI	51080103 <sub>H</sub>
XC824M-1FGI	51080122 <sub>H</sub>
XC824MT-1FGI	51080102 <sub>H</sub>

## 3 Electrical Parameters

**Chapter 3** provides the characteristics of the electrical parameters which are implementation-specific for the XC822/824.

### 3.1 General Parameters

The general parameters are described here to aid the users in interpreting the parameters mainly in **Section 3.2** and **Section 3.3**.

#### 3.1.1 Parameter Interpretation

The parameters listed in this section represent partly the characteristics of the XC822/824 and partly its requirements on the system. To aid interpreting the parameters easily when evaluating them for a design, they are indicated by the abbreviations in the "Symbol" column:

- **CC**
  - These parameters indicate **C**ontroller **C**haracteristics, which are distinctive features of the XC822/824 and must be regarded for a system design.
- **SR**
  - These parameters indicate **S**ystem **R**equirements, which must be provided by the microcontroller system in which the XC822/824 is designed in.



### 3.1.2 Absolute Maximum Rating

Maximum ratings are the extreme limits to which the XC822/824 can be subjected to without permanent damage.

**Table 6 Absolute Maximum Rating Parameters**

Parameter	Symbol	Limit Values		Unit	Notes
		Min.	Max.		
Ambient temperature	$T_A$	-40	125	°C	under bias
Storage temperature	$T_{ST}$	-65	150	°C	–
Junction temperature	$T_J$	-40	150	°C	under bias
Voltage on power supply pin with respect to $V_{SS}$	$V_{DDP}$	-0.5	6	V	
Maximum current per pin for P1[3:0]	$I_M$	-90	90	mA	
Input current on any pin during overload condition	$I_{IN}$	-10	10	mA	
Absolute sum of all input currents during overload condition	$\Sigma I_{IN} $	–	tbd	mA	

*Note: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. During absolute maximum rating overload conditions ( $V_{IN} > V_{DDP}$  or  $V_{IN} < V_{SS}$ ) the voltage on  $V_{DDP}$  pin with respect to ground ( $V_{SS}$ ) must not exceed the values defined by the absolute maximum ratings.*

### 3.1.3 Operating Condition

The following operating conditions must not be exceeded in order to ensure correct operation of the XC822/824. All parameters mentioned in the following tables refer to these operating conditions, unless otherwise noted.

**Table 7 Operating Condition Parameters**

Parameter	Symbol	Limit Values		Unit	Notes/ Conditions
		Min.	Max.		
Digital power supply voltage	$V_{DDP}$	3.0	5.5	V	
		2.5	3.0	V	<sup>1)</sup>
CPU Clock Frequency	$f_{CCLK}$	22.5	25.6	MHz	typ. 24 MHz
		7.5	8.5	MHz	typ. 8 MHz
Ambient temperature	$T_A$	-40	85	°C	SAF-XC822/824...
		-40	125	°C	SAK-XC824...

1) In this voltage range, limited operations are available in active mode. Operations in power save modes are fully supported.

### 3.2 DC Parameters

The electrical characteristics of the DC Parameters are detailed in this section.

#### 3.2.1 Input/Output Characteristics

**Table 8** provides the characteristics of the input/output pins of the XC822/XC824.

**Table 8 Input/Output Characteristics of XC822/XC824 (Operating Conditions apply)**

Parameter	Symbol		Limit Values		Unit	Test Conditions
			Min.	Max.		
Output low voltage on port pins	$V_{OLP}$	CC	–	1.0	V	$I_{OL} = 25 \text{ mA (5 V)}$ $I_{OL} = 13 \text{ mA (3.3 V)}$
			–	0.4	V	$I_{OL} = 10 \text{ mA (5 V)}$ $I_{OL} = 5 \text{ mA (3.3 V)}$
Output high voltage on port pins	$V_{OHP}$	CC	$V_{DDP} - 1.0$	–	V	$I_{OH} = -15 \text{ mA (5 V)}$ $I_{OH} = -8 \text{ mA (3.3 V)}$
			$V_{DDP} - 0.4$	–	V	$I_{OH} = -5 \text{ mA (5 V)}$ $I_{OH} = -2.5 \text{ mA (3.3 V)}$
Input low voltage on port pins	$V_{ILP}$	SR	–	$0.3 \times V_{DDP}$	V	CMOS Mode
Input high voltage on port pins	$V_{IHP}$	SR	$0.7 \times V_{DDP}$	–	V	CMOS Mode
Input Hysteresis <sup>1)</sup>	$HYS$	CC	$0.08 \times V_{DDP}$	–	V	CMOS Mode (5 V)
			$0.03 \times V_{DDP}$	–	V	CMOS Mode (3.3 V)
			tbd	–	V	CMOS Mode (2.5 V)
Pull-up current on port pins	$I_{PUP}$	CC	–	-20	$\mu\text{A}$	$V_{IH,min}$ (5 V)
			-150	–	$\mu\text{A}$	$V_{IL,max}$ (5 V)
			–	-5	$\mu\text{A}$	$V_{IH,min}$ (3.3 V)
			-100	–	$\mu\text{A}$	$V_{IL,max}$ (3.3 V)

**Preliminary**
**Electrical Parameters**
**Table 8 Input/Output Characteristics of XC822/XC824 (Operating Conditions apply) (cont'd)**

Parameter	Symbol		Limit Values		Unit	Test Conditions
			Min.	Max.		
Pull-down current on port pins	$I_{PDP}$	CC	–	20	$\mu\text{A}$	$V_{IL,max}$ (5 V)
			150	–	$\mu\text{A}$	$V_{IH,min}$ (5 V)
			–	5	$\mu\text{A}$	$V_{IL,max}$ (3.3 V)
			100	–	$\mu\text{A}$	$V_{IH,min}$ (3.3 V)
Input leakage current on port pins <sup>2)</sup>	$I_{OZP}$	CC	-1	1	$\mu\text{A}$	$0 < V_{IN} < V_{DDP}$ , $T_A \leq 125\text{ }^\circ\text{C}$
Overload current on any pin	$I_{OVP}$	SR	-5	5	mA	–
Absolute sum of overload currents	$\Sigma I_{OV} $	SR	–	25	mA	<sup>3)</sup>
Voltage on any pin during $V_{DDP}$ power off	$V_{PO}$	SR	–	0.3	V	<sup>4)</sup>
Maximum current per pin (excluding $V_{DDP}$ and $V_{SS}$ )	$I_M$	SR	-15	25	mA	–
Maximum current into $V_{DDP}$	$I_{MVDDP}$	SR	–	80	mA	
Maximum current out of $V_{SS}$	$I_{MVSS}$	SR	–	80	mA	

1) Not subjected to production test, verified by design/characterization. Hysteresis is implemented to avoid meta stable states and switching due to internal ground bounce. It cannot be guaranteed that it suppresses switching due to external system noise.

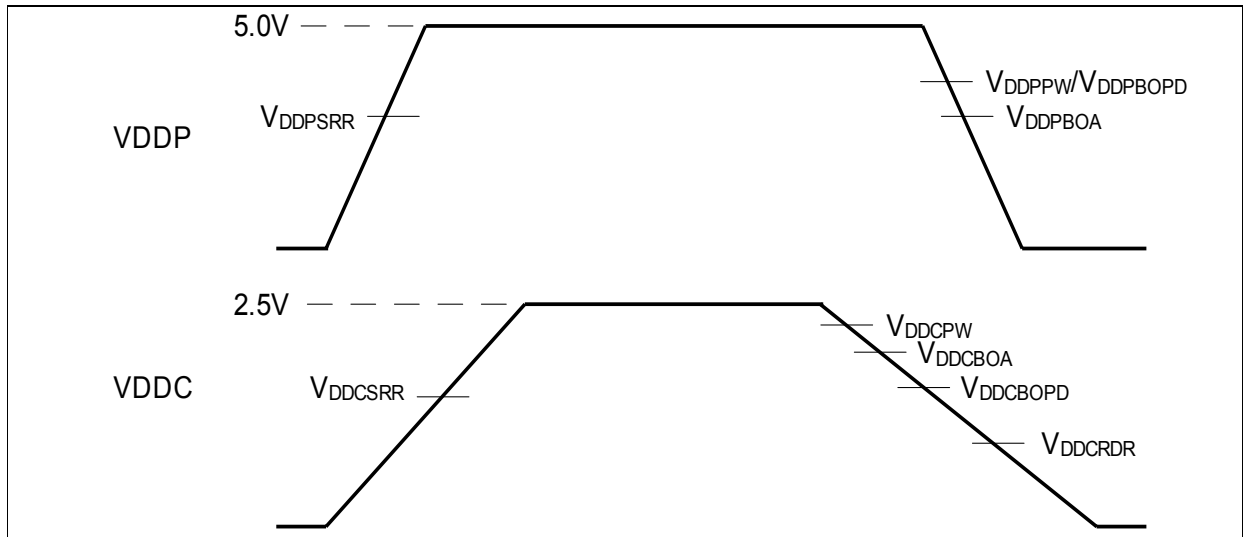
2) An additional error current ( $I_{INJ}$ ) will flow if an overload current flows through an adjacent pin.

3) Not subjected to production test, verified by design/characterization.

4) Not subjected to production test, verified by design/characterization. However, for applications with strict low power-down current requirements, it is mandatory that no active voltage source is supplied at any GPIO pin when  $V_{DDP}$  is powered off.

### 3.2.2 Supply Threshold Characteristics

**Table 9** provides the characteristics of the supply threshold in the XC822/824.



**Figure 8** Supply Threshold Parameters

**Table 9** Supply Threshold Parameters (Operating Conditions apply)

Parameters	Symbol	CC	Limit Values			Unit
			Min.	Typ.	Max.	
$V_{DDP}$ prewarning voltage <sup>1)</sup>	$V_{DDPPW}$	CC		3.6		V
$V_{DDP}$ brownout voltage in active mode <sup>2)</sup>	$V_{DDPBOA}$	CC			2.9	V
$V_{DDP}$ brownout voltage in all power down mode <sup>2)</sup>	$V_{DDPBOPD}$			3.6		V
$V_{DDP}$ system reset release voltage <sup>3)</sup>	$V_{DDPSRR}$	CC			2.9	V
$V_{DDC}$ prewarning voltage <sup>4)</sup>	$V_{DDCPW}$	CC		2.4		V
$V_{DDC}$ brownout voltage in active mode	$V_{DDCBOA}$	CC		2.3		V
$V_{DDC}$ brownout voltage in all power down mode	$V_{DDCBOPD}$	CC		1.5		V
$V_{DDC}$ system reset release voltage <sup>3)</sup>	$V_{DDCSRR}$	CC		2.3		V
RAM data retention voltage	$V_{DDCRDR}$	CC	1.1			V

1) Detection is enabled via SDCON register in active mode. It is automatically disabled in power down mode. Detection should be disabled for external power supply of less than 4.5 V.

2) Detection is enabled via SDCON register. Detection must be disabled for external power supply of less than 3 V.

3)  $V_{DDPSRR}$  and  $V_{DDCSRR}$  must be met before the system reset is released.

4) Detection is enabled via SDCON register in active mode. It is automatically disabled in power down mode.

### 3.2.3 ADC Characteristics

The values in [Table 10](#) are given for an analog power supply of 5.0 V. The ADC can be used with an analog power supply down to 3 V. But in this case, analog parameters may show a reduced performances. In the reduced voltage mode, the ADC is not recommended to be used ( $2.5 V < V_{DDP} < 3 V$ ).

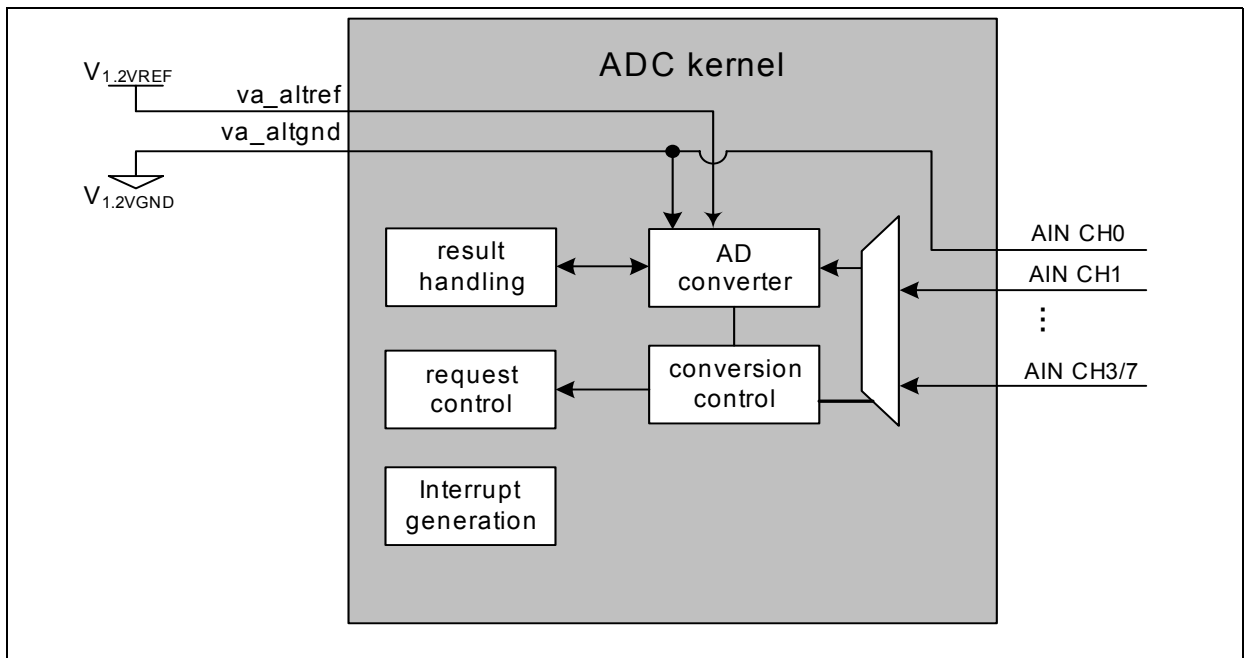
**Table 10 ADC Characteristics (Operating Conditions apply;  $V_{DDP} = 5 V$ )**

Parameter	Symbol		Limit Values			Unit	Test Conditions / Remarks
			Min.	Typ.	Max.		
Analog reference voltage	$V_{AREF}$		–	$V_{DDP}$	–	V	Connect internally to $V_{DDP}$
Analog reference ground	$V_{AGND}$		–	$V_{SSP}$	–	V	Connect internally to $V_{SSP}$
Alternate analog reference ground	$V_{AGNDALT}$	SR	$V_{SSP} - 0.1$	–	$2.5^{1)}$	V	Connect to AN0 in differential mode, See <a href="#">Figure 9</a> .
Analog input voltage range	$V_{AIN}$	SR	$V_{AGND}$	–	$V_{AREF}$	V	–
ADC clock	$f_{ADCI}$		8	–	16	MHz	internal analog clock
Sample time	$t_S$	CC	$(2 + INPCR0.STC) \times t_{ADCI}$			$\mu s$	–
Conversion time	$t_C$	CC	See <a href="#">Section 3.2.3.1</a>			$\mu s$	–
Total unadjusted error	TUE <sup>2)</sup>	CC	–	–	$\pm 1$	LSB	8-bit conversion with internal reference <sup>3)</sup>
			–	–	$\pm tbd$	LSB	10-bit conversion with internal reference <sup>3)4)</sup>
			–	–	$\pm tbd$	LSB	12/13-bit conversion using the Low Pass Filter
Differential Nonlinearity	DNL	CC	–	tbd	–	LSB	10-bit conversion
Integral Nonlinearity	INL	CC	–	tbd	–	LSB	10-bit conversion
Offset	OFF	CC	–	tbd	–	LSB	10-bit conversion
Gain	GAIN	CC	–	tbd	–	LSB	10-bit conversion

**Table 10 ADC Characteristics (Operating Conditions apply;  $V_{DDP} = 5\text{ V}$ )**

Parameter	Symbol		Limit Values			Unit	Test Conditions / Remarks
			Min.	Typ.	Max.		
Switched capacitance at an analog input	$C_{AINSW}$	CC	–	2	3	pF	3)5)
Total capacitance at an analog input	$C_{AINT}$	CC	–	–	12	pF	3)5)
Input resistance of an analog input	$R_{AIN}$	CC	–	1.5	2	k $\Omega$	3)

- 1) 1.2 V at  $V_{DDP} = 3.0\text{ V}$ .
- 2) TUE is tested at  $V_{DDP} = 5.0\text{ V}$ .
- 3) Not subject to production test, verified by design/characterization
- 4) If a reduced positive reference voltage is used, TUE will increase. If the positive reference is reduced by a factor of K, the TUE will increased by 1/K. Example:K = 0.8, 1/K = 1.25; 1.25 X TUE = 2.5 LSB10
- 5) The sampling capacity of the conversion C-Network is pre-charged to  $V_{AREF}/2$  before connecting the input to the C-Network. Because of the parasitic elements, the voltage measured at ANx is lower than  $V_{AREF}/2$ .



**Figure 9 Differential like measurement with internal 1.2V voltage reference, and CH0 gnd.**

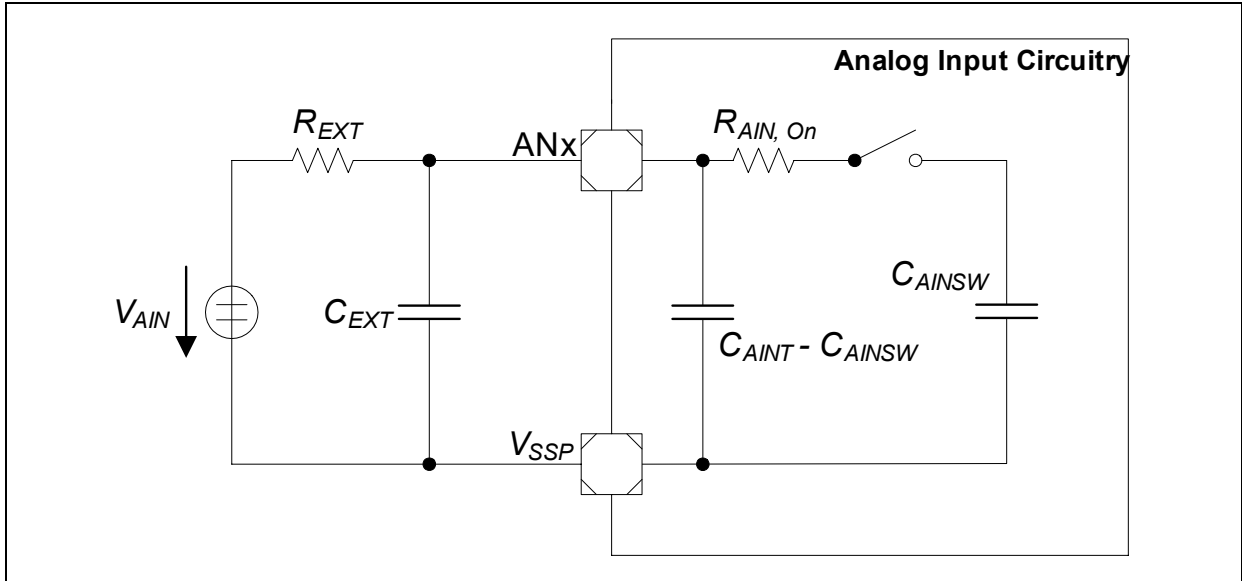


Figure 10 ADC Input Circuits

### 3.2.3.1 ADC Conversion Timing

Conversion time,  $t_C = t_{ADC} \times (1 + r \times (3 + n + STC))$ , where

- $r = CTC + 3$ ,
- CTC = Conversion Time Control (GLOBCTR.CTC),
- STC = Sample Time Control (INPCR0.STC),
- $n = 8$  or  $10$  (for 8-bit and 10-bit conversion respectively),
- $t_{ADC} = 1 / f_{ADC}$



**3.2.3.2 Out of Range Comparator Characteristics**

**Table 11** below shows the Out of Range Comparator characteristics.

**Table 11 Out of Range Comparator Characteristics (Operating Conditions apply)<sup>1)</sup>**

Parameter	Symbol	Limit Values			Unit	Remarks
		Min.	Typ.	Max.		
DC Switching Level	$V_{SenseDC}$	60	125	270	mV	Above $V_{DDP}$
DC Hysteresis	$V_{SenseHys}$	30	–	–	mV	
Pulse Width	$t_{SensePW}$	300	–	–	ns	$ANx > V_{DDP}$
Switching Delay	$t_{SenseSD}$	–	–	400	ns	$ANx \geq V_{DDP} + 350 \text{ mV}$
Pulse Switching Level	$t_{SensePSL}$	–	250	–	mV	@ 300 nsec
		–	60	–	mV	@ 800 usec

1) Not all parameters are 100% tested, but are verified by design/characterisation and test correlation.

### 3.2.4 Flash Memory Parameters

The XC822/824 is delivered with all Flash sectors erased (read all zeros).

The data retention time of the XC822/824's Flash memory (i.e. the time after which stored data can still be retrieved) depends on the number of times the Flash memory has been erased and programmed.

*Note: Flash memory parameters are not subject to production test but verified by design and/or characterization.*

**Table 12 Flash Timing Parameters (Operating Conditions apply)**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Read access time (per byte)	$t_{ACC}$ CC	–	125	-	ns	
Programming time per wordline	$t_{PR}$ CC	–	2.2	-	ms	
Erase time (one or more sectors)	$t_{ER}$ CC	–	120	-	ms	

**Table 13 Flash Data Retention and Endurance (Operating Conditions apply)**

Retention	Endurance <sup>1)</sup>	Size	Remarks
20 years	1,000 cycles	up to 8 Kbytes	
5 years	10,000 cycles	1 Kbyte	
2 years	70,000 cycles	512 bytes	
2 years	100,000 cycles	128 bytes	

1) One cycle refers to the programming of all wordlines in a sector and erasing of sector. The Flash endurance data specified in [Table 13](#) is valid only if the following conditions are fulfilled:

- the maximum number of erase cycles per Flash sector must not exceed 100,000 cycles.
- the maximum number of erase cycles per Flash bank must not exceed 300,000 cycles.
- the maximum number of program cycles per Flash bank must not exceed 2,500,000 cycles.

**Table 14 Emulated Flash Data Retention and Endurance based on EEPROM Emulation ROM Library (Operating Conditions apply)**

Retention	Endurance <sup>1)</sup>	Emulation Size	Remarks
2 years	1,600,000 cycles	31 bytes	
2 years	1,400,000 cycles	62 bytes	
2 years	1,200,000 cycles	93 bytes	
2 years	1,000,000 cycles	124 bytes	

1) These values show the maximum endurance. Maximum endurance is the maximum possible unique data write if each data update is only 31 bytes. Minimum endurance cycle is the maximum possible unique data write if each data update is the same as the emulation size. The minimum endurance cycle can be calculated using the formulae [(max. endurance)\*(31)/(emulation size)].

**3.2.5 Power Supply Current**

**Table 15** provides the characteristics of the power supply current in the XC822/824.

**Table 15 Power Consumption Parameters<sup>1) 2)</sup>(Operating Conditions apply)**

Parameter	Symbol	Limit Values		Unit	Test Condition
		Typ.	Max.		
Active Mode	$I_{DDPA}$	23	31	mA	5 V <sup>3)</sup>
		15	22	mA	5 V <sup>4)</sup>
		–	5	mA	2.5 V <sup>5)</sup>
Idle Mode	$I_{DDPI}$	18	25	mA	5 V <sup>6)</sup>
		–	5	mA	2.5 V <sup>5)</sup>
Power Down Mode 1	$I_{PDP1}$	3	5	μA	$T_A = 25^\circ\text{C}^{7)}$
		–	tbd	μA	$T_A = 85^\circ\text{C}^{7)8)}$
Power Down Mode 2	$I_{PDP2}$	5	8	μA	$T_A = 25^\circ\text{C}^{7)}$
		–	tbd	μA	$T_A = 85^\circ\text{C}^{7)8)}$

- 1) The typical  $I_{DDP}$  values are based on preliminary measurements and are to be used as reference only. These values are periodically measured at  $T_A = +25^\circ\text{C}$  and  $V_{DDP} = 5\text{ V}$  for 5 V range and 3.3 V for 3 V range.
- 2) The maximum  $I_{DDC}$  values are measured under worst case conditions ( $T_A = +125^\circ\text{C}$  and  $V_{DDC} = 5\text{ V}$ ).
- 3)  $I_{DDP}$  (active mode) is measured with: CPU clock and input clock to all peripherals running at 24 MHz (CLKMODE=0).
- 4)  $I_{DDP}$  (active mode) is measured with: CPU clock and input clock to all peripherals running at 8 MHz (CLKMODE=1).
- 5) This value is based on the maximum load capacity of EVR during  $V_{DDP} = 2.5\text{ V}$ . Not subject to production test, verified by design/characterisation.
- 6)  $I_{DDP}$  (idle mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 24 MHz (CLKMODE=0).
- 7)  $I_{PDP}$  is measured at 5 V and 3.3 V with: wake-up port is programmed to be input with either internal pull devices enabled or driven externally to ensure no floating inputs.
- 8) Not subject to production test, verified by design/characterisation.

**Preliminary**
**Electrical Parameters**

**Table 16** shows the maximum active current within the device in the reduced voltage condition of  $2.5\text{ V} < V_{\text{DDP}} < 3.0\text{ V}$ . The active current consumption needs to be below the specified values as according to the  $V_{\text{DDP}}$  voltage. If the conditions are not met, a brownout reset may be triggered.

**Table 16 Active Current Consumption in Reduced Voltage Condition**

$V_{\text{DDP}}$	2.5 V	2.6 V	2.7 V	2.8 V
<b>Maximum active current</b>	7 mA	13 mA	20 mA	25 mA

**Table 17** provides the active current consumption of some modules operating at 8 MHz active mode, 3 V power supply at  $25^\circ\text{C}$ . The typical values shown are used as a reference guide for device operating in reduced voltage conditions.

**Table 17 Typical Active Current Consumption<sup>1) 2)</sup>**

Active Current Consumption	Symbol	Limit Values	Unit	Test Condition
		Typ.		
Baseload current <sup>3)</sup>	$I_{\text{CPUDDC}}$	5850	$\mu\text{A}$	Modules including Core, memories, UART, T0, T1 and EVR. Disable ADC analog (GLOBCTR.ANON = 0).
ADC <sup>4)</sup>	$I_{\text{ADCDDC}}$	3390	$\mu\text{A}$	Set PMCON1.ADC_DIS to 0 and GLOBECTR.ANON to 1
SSC <sup>5)</sup>	$I_{\text{SSCDDC}}$	460	$\mu\text{A}$	Set PMCON1.SSC_DIS to 0
CCU6 <sup>6)</sup>	$I_{\text{CCU6DDC}}$	3320	$\mu\text{A}$	Set PMCON1.CCU_DIS to 0
Timer 2 <sup>7)</sup>	$I_{\text{T2DDC}}$	200	$\mu\text{A}$	Set PMCON1.T2_DIS to 0
MDU <sup>8)</sup>	$I_{\text{MDUDDC}}$	1260	$\mu\text{A}$	Set PMCON1.MDU_DIS to 0
LEDTSCU <sup>9)</sup>	$I_{\text{LEDDDC}}$	520	$\mu\text{A}$	Set PMCON1.LTS_DIS to 0
IIC <sup>10)</sup>	$I_{\text{IICDDC}}$	580	$\mu\text{A}$	Set PMCON1.IIC_DIS to 0

1) Modules that are controllable by programming the register PMCON1.

2) Not subject to production test, verified by design/characterisation.

3) Baseload current is measured when the device is running in user mode with an endless loop in the flash memory. All modules in register PMCON1 are disabled.

4) ADC active current is measured with: module enable, ADC analog clock at 8MHz, running in parallel conversion request in autoscan mode for 4 channels

5) SSC active current is measured with: module enabled, running in loop back mode at a baud rate of 1 MBaud

6) CCU6 active current is measured with: module enabled, all timers running in 8 MHz, 6 PWM outputs are generated.

7) Timer 2 active current is measured with: module enabled, timer running in 8 MHz

8) MDU active current is measured with: module enabled, division operation was performed.

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**Preliminary****Electrical Parameters**

- 9) LEDTSCU active current is measured with: module enabled, counter running in 8 MHz.
- 10) IIC active current is measured with: module enabled, performing a master transmit with the master clock running at 400 KHz.

### 3.3 AC Parameters

The electrical characteristics of the AC Parameters are detailed in this section.

#### 3.3.1 Testing Waveforms

The testing waveforms for rise/fall time, output delay and output high impedance are shown in [Figure 11](#), [Figure 12](#) and [Figure 13](#).

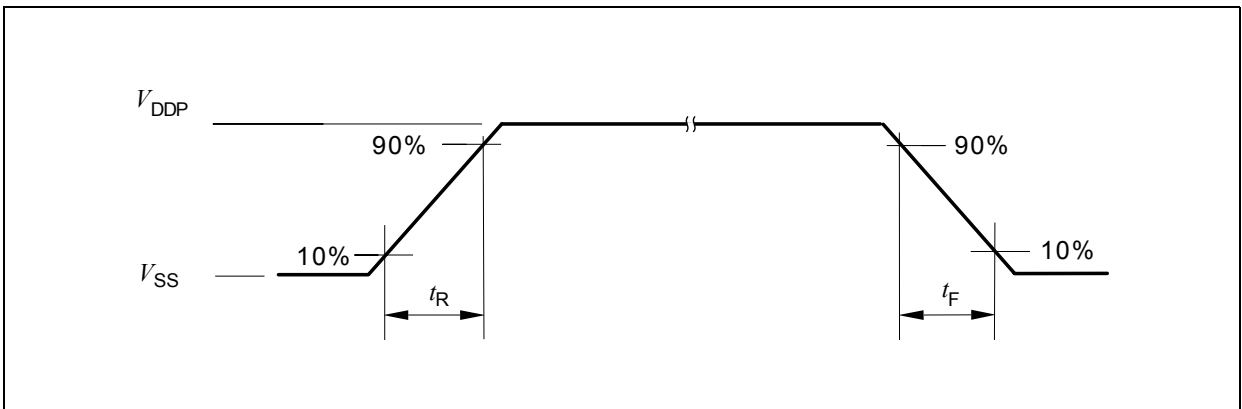


Figure 11 Rise/Fall Time Parameters

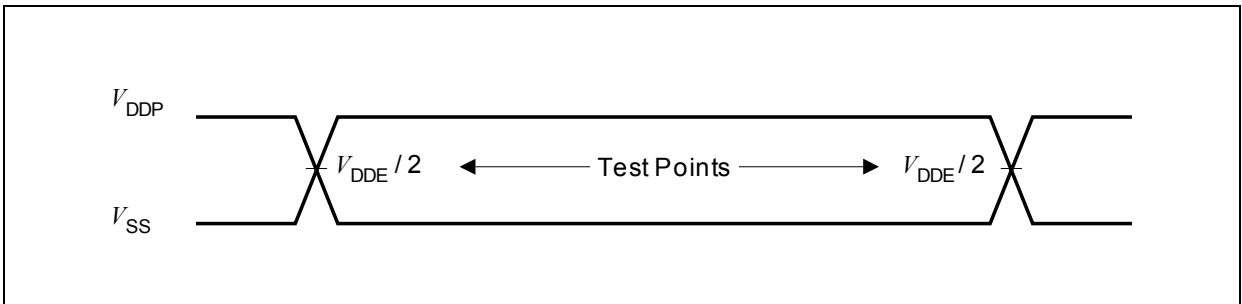


Figure 12 Testing Waveform, Output Delay

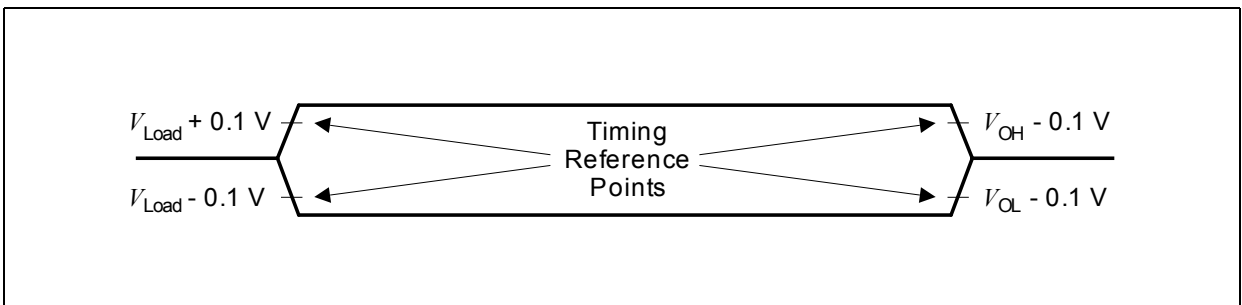


Figure 13 Testing Waveform, Output High Impedance

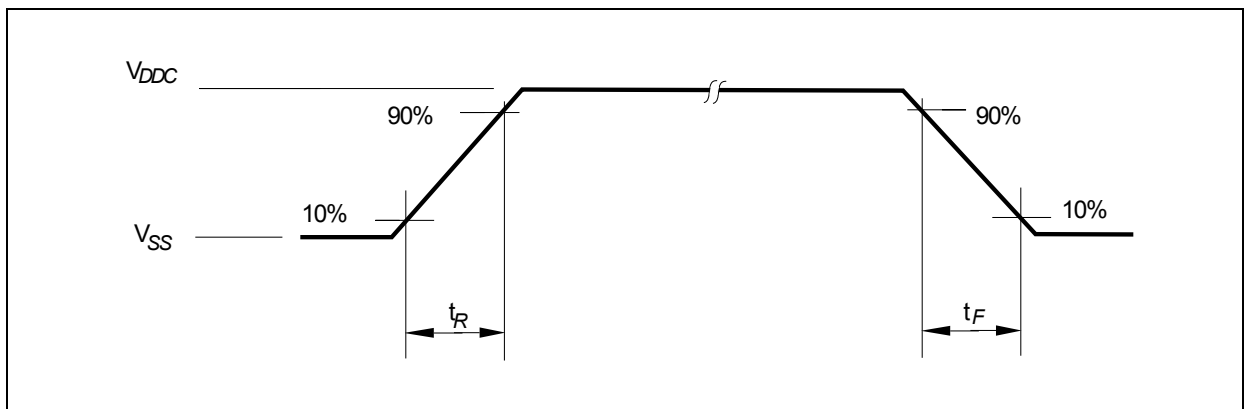
### 3.3.2 Output Rise/Fall Times

Table 18 provides the characteristics of the output rise/fall times in the XC822/824.

**Table 18 Output Rise/Fall Times Parameters (Operating Conditions apply)**

Parameter	Symbol	Limit Values		Unit	Test Conditions
		Min.	Max.		
Rise/fall times on Standard Pad <sup>1)2)</sup>	$t_R, t_F$	–	10	ns	20 pF <sup>3)4)</sup> (5 V & 3.3 V).

- 1) Rise/Fall time parameters are taken with 10% - 90% of supply.
- 2) Not all parameters are 100% tested, but are verified by design/characterisation and test correlation.
- 3) Additional rise/fall time valid for  $C_L = 20 \text{ pF} - C_L = 100 \text{ pF}$  @ 0.125 ns/pF at 5 V supply voltage.
- 4) Additional rise/fall time valid for  $C_L = 20 \text{ pF} - C_L = 100 \text{ pF}$  @ 0.225 ns/pF at 3.3 V supply voltage.



**Figure 14 Rise/Fall Times Parameters**



### 3.3.3 Oscillator Timing and Wake-up Timing

**Table 19** provides the characteristics of the power-on reset, PLL and Wake-up timings in the XC822/824.

**Table 19 Power-On Reset Wake-up Timing<sup>1)</sup> (Operating Conditions apply)**

Parameter	Symbol	Limit Values			Unit	Test Conditions
		Min.	Typ.	Max.		
48 MHz Oscillator start-up time	$t_{48\text{MOSCST}}$ CC	–	–	13	μs	
75 KHz Oscillator start-up time	$t_{75\text{KOSCST}}$ CC	–	–	800	μs	
Flash initialization time	$t_{\text{FINT}}$ CC	–	160	–	μs	

1) Not subject to production test, verified by design/characterisation.

**3.3.4 On-Chip Oscillator Characteristics**

**Table 20** provides the characteristics of the 48 MHz oscillator in the XC822/824.

**Table 20 48 MHz Oscillator Characteristics (Operating Conditions apply)**

Parameter	Symbol	Limit Values			Unit	Test Conditions
		Min.	Typ.	Max.		
Nominal frequency	$f_{\text{NOM}}$ CC	-0.5 %	48	+0.5%	MHz	under nominal conditions <sup>1)</sup> after trimming
Long term frequency deviation	$\Delta f_{\text{LT}}$ CC	-2.5	–	3	%	with respect to $f_{\text{NOM}}$ , over lifetime and temperature (0 °C to 85 °C)
		-4.5	–	4.5	%	with respect to $f_{\text{NOM}}$ , over lifetime and temperature (-40 °C to 125 °C)
Short term frequency deviation (over full range of $V_{\text{DDC}}$ )	$\Delta f_{\text{ST}}$ CC	-1	–	1	%	with respect to $f_{\text{NOM}}$ , within one LIN message (< 10 ms ... 100 ms)
Overall frequency Drift	$\Delta f_{\text{OD}}$ CC	-5.5	–	5.5	%	with respect to $f_{\text{NOM}}$ , over voltage and temperature deviation

1) Nominal condition:  $V_{\text{DDC}} = 2.5 \text{ V}$ ,  $T_{\text{A}} = + 25^{\circ}\text{C}$ .

**Table 21** provides the characteristics of the 75 kHz oscillator in the XC822/824.

**Table 21 75 kHz Oscillator Characteristics (Operating Conditions apply)**

Parameter	Symbol	CC	Limit Values			Unit	Test Conditions
			Min.	Typ.	Max.		
Nominal frequency	$f_{\text{NOM}}$	CC	-1%	75	+1%	KHz	under nominal conditions <sup>1)</sup> after trimming
Long term frequency deviation	$\Delta f_{\text{LT}}$	CC	-4.5	–	4.5	%	with respect to $f_{\text{NOM}}$ , over lifetime and temperature (-40 °C to 125 °C)
Short term frequency deviation (over full range of $V_{\text{DDC}}$ )	$\Delta f_{\text{ST}}$	CC	-1.5	–	1.5	%	with respect to $f_{\text{NOM}}$ , within one LIN message (< 10 ms ... 100 ms)

1) Nominal condition:  $V_{\text{DDC}} = 2.5 \text{ V}$ ,  $T_{\text{A}} = + 25^{\circ}\text{C}$ .

### 3.3.5 SSC Timing

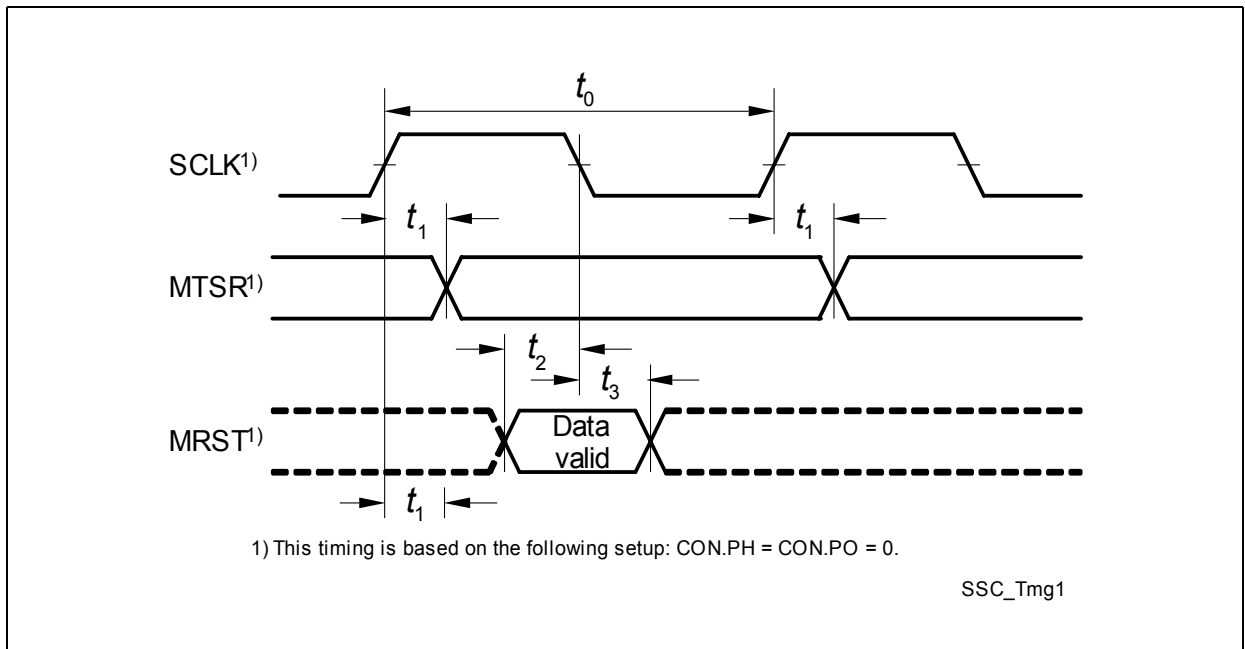
#### 3.3.5.1 SSC Master Mode Timing

Table 22 provides the SSC master mode timing in the XC822/824.

**Table 22 SSC Master Mode Timing (Operating Conditions apply; CL = 50 pF)**

Parameter	Symbol		Limit Values		Unit
			Min.	Max.	
SCLK clock period	$t_0$	CC	$2 * T_{SSC}^{1)}$	–	ns
MTSR delay from SCLK	$t_1$	CC	0	tbd	ns
MRST setup to SCLK	$t_2$	SR	tbd	–	ns
MRST hold from SCLK	$t_3$	SR	tbd	–	ns

1)  $T_{SSCmin} = T_{CPU} = 1/f_{CPU}$ . When  $f_{CPU} = 24$  MHz,  $t_0 = 83.3$  ns.  $T_{CPU}$  is the CPU clock period.



**Figure 15 SSC Master Mode Timing**

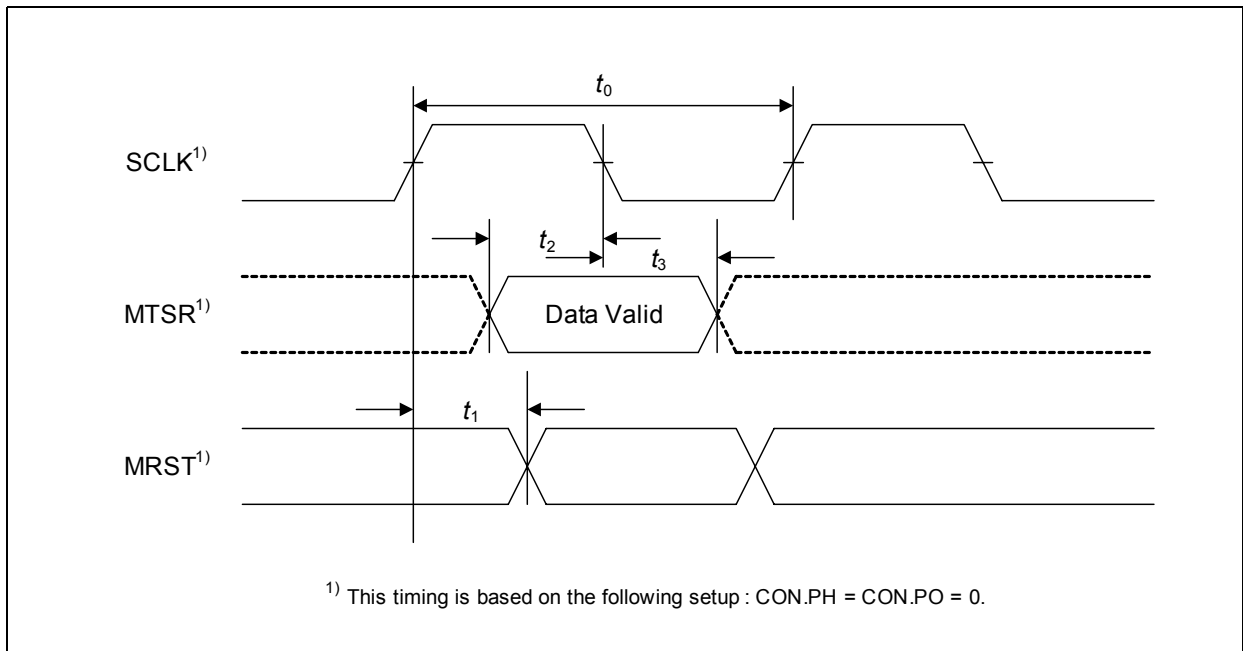
### 3.3.5.2 SSC Slave Mode Timing

Table 23 provides the SSC slave mode timing in the XC822/824.

**Table 23 SSC Slave Mode Timing (Operating Conditions apply; CL = 50 pF)**

Parameter	Symbol		Limit Values		Unit
			Min.	Max.	
SCLK clock period	$t_0$	SR	$4 * T_{SSC}^{1)}$	–	ns
MRST delay from SCLK	$t_1$	CC	0	tbd	ns
MTSR setup to SCLK	$t_2$	SR	tbd	–	ns
MTSR hold from SCLK	$t_3$	SR	tbd	–	ns

1)  $T_{SSCmin} = T_{CPU} = 1/f_{CPU}$ . When  $f_{CPU} = 24$  MHz,  $t_0 = 166.7$  ns.  $T_{CPU}$  is the CPU clock period.



**Figure 16 SSC Slave Mode Timing**

### 3.3.6 SPD Timing

The SPD interface will work with standard SPD tools having a sample/output clock frequency deviation of +/- 5% or less. For further details please refer to application note AP24004 in section SPD Timing Requirements.

*Note: These parameters are no subject to product test but verified by design and/or characterization.*

*Note: Operating Conditions apply.*

## 4 Package and Quality Declaration

**Chapter 4** provides the information of the XC822/824 package and reliability section.

### 4.1 Package Parameters

**Table 24** provides the thermal characteristics of the packages used in XC822 and XC824 respectively.

**Table 24 Thermal Characteristics of the Packages**

Parameter	Symbol		Limit Values		Unit	Package Types
			Min.	Max.		
Thermal resistance junction case <sup>1)</sup>	$R_{TJC}$	CC	-	36.2	K/W	PG-TSSOP-16-1
			-	34.3	K/W	PG-DSO-20-45
Thermal resistance junction lead <sup>1)</sup>	$R_{TJL}$	CC	-	356.6	K/W	PG-TSSOP-16-1
			-	36.2	K/W	PG-DSO-20-45

1) The thermal resistances between the case and the ambient ( $R_{TCA}$ ), the lead and the ambient ( $R_{TLA}$ ) are to be combined with the thermal resistances between the junction and the case ( $R_{TJC}$ ), the junction and the lead ( $R_{TJL}$ ) given above, in order to calculate the total thermal resistance between the junction and the ambient ( $R_{TJA}$ ). The thermal resistances between the case and the ambient ( $R_{TCA}$ ), the lead and the ambient ( $R_{TLA}$ ) depend on the external system (PCB, case) characteristics, and are under user responsibility.

The junction temperature can be calculated using the following equation:  $T_J = T_A + R_{TJA} \times P_D$ , where the  $R_{TJA}$  is the total thermal resistance between the junction and the ambient. This total junction ambient resistance  $R_{TJA}$  can be obtained from the upper four partial thermal resistances, by

- simply adding only the two thermal resistances (junction lead and lead ambient), or
- by taking all four resistances into account, depending on the precision needed.

### 4.2 Package Outline

Figure 17 and Figure 18 shows the package outlines of the XC822 (TSSOP-16) and XC824 (DSO-20) devices respectively.

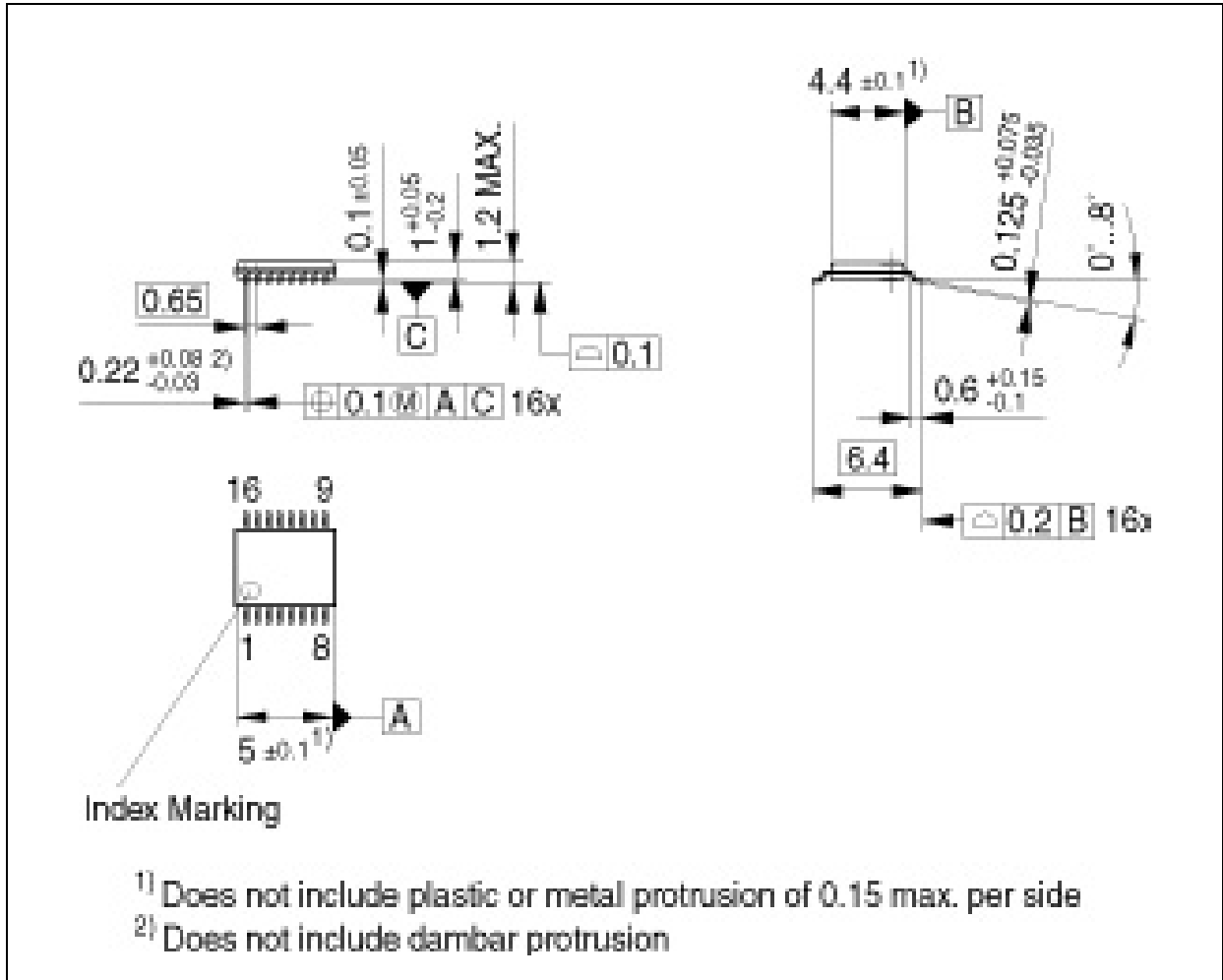


Figure 17 PG-TSSOP-16-1 Package Outline



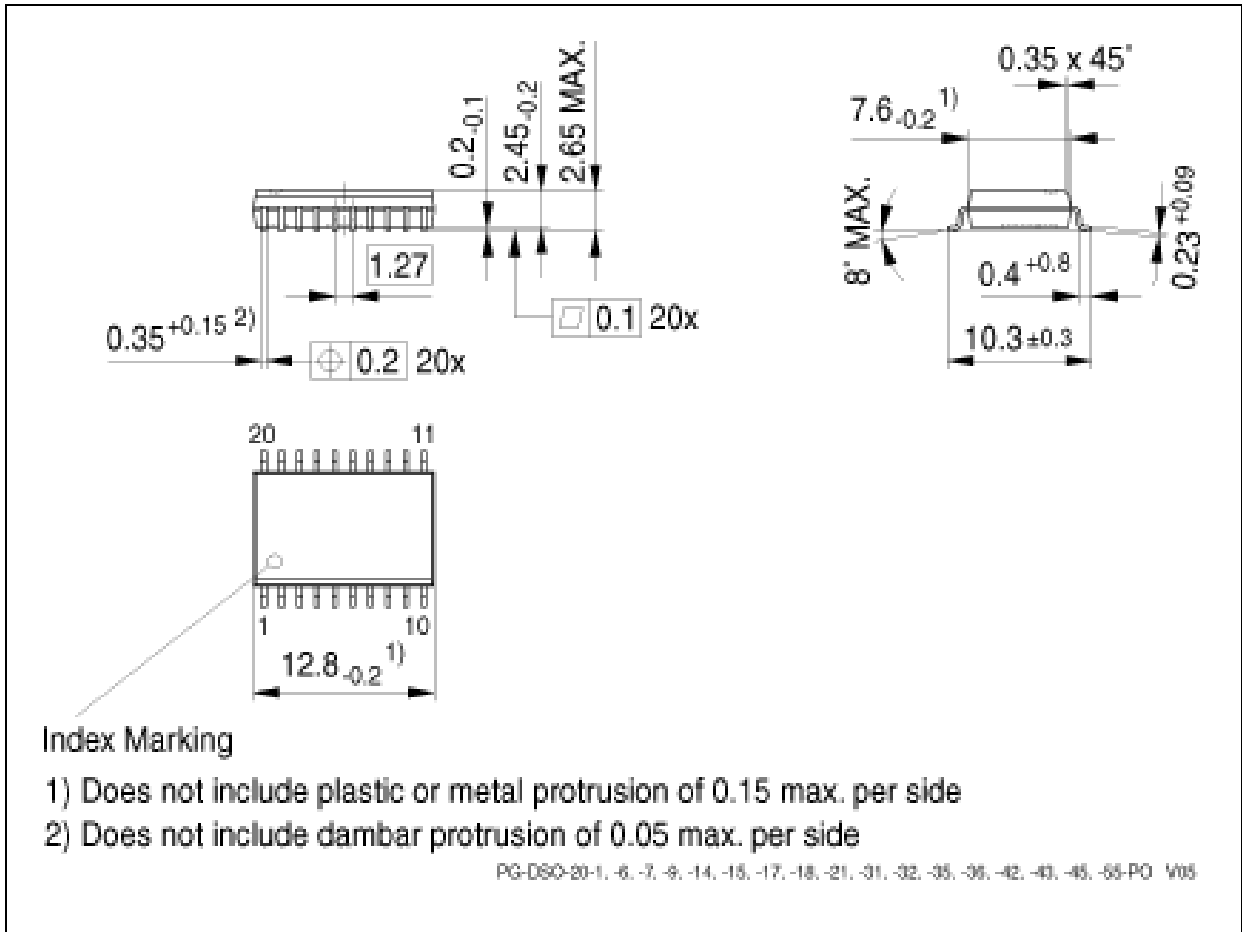


Figure 18 PG-DSO-20-45 Package Outline

### 4.3 Quality Declaration

Table 25 shows the characteristics of the quality parameters in the XC822/824.

**Table 25 Quality Parameters**

Parameter	Symbol	Limit Values		Unit	Notes
		Min.	Max.		
ESD susceptibility according to Human Body Model (HBM)	$V_{HBM}$	-	2000	V	Conforming to EIA/JESD22-A114-B
ESD susceptibility according to Charged Device Model (CDM) pins	$V_{CDM}$	-	500	V	Conforming to JESD22-C101-C

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